

T-M3.2

Wire Bond Globe Top Package
For contact based application (Memory)

Short Product Overview

May 2010

Chip Card & Security

T-M3.2 Short Product Overview	Ref.: SPO_T-M3.2_1005
Revision History: Current Version 05.10	
Previous Releases:	
Page	

Important: Further information is confidential and on request. Please contact:
Infineon Technologies AG in Munich, Germany,
Chip Card & Security ICs,
E-Mail: security.chipcard.ics@infineon.com

Edition 2010

**Published by Infineon Technologies AG,
Chip Card & Security
81726 Munich, Germany
© Infineon Technologies AG 2010
All Rights Reserved.**

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party

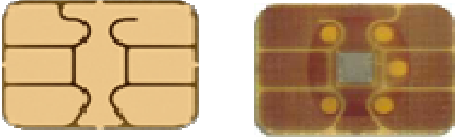
Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Product name	T-M3.2
Picture	
Product description	Contact based module 6 contacts Epoxy Tape Chip Cavity Wire Bond Glob Top
Typical Applications	Healthcare/, Ticketing, Loyalty, Access Control
Pitch	9.5 mm
Dimensions	11 x 8.3 mm
Thickness	max. 580µm
Contact Surface	CIN
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	

Information

For further information on technology, delivery forms and conditions please contact your nearest Infineon Technologies sales representative (www.infineon.com).

www.infineon.com

Published by Infineon Technologies AG